



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN 20150112002  
TLE4275QKVURQ1 Cu wire and Mold Compound change  
Final Change Notification**

**Date:** 2/12/2015  
**To:** Newark/Farnell PCN

Dear Customer:

This is an announcement of change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

If samples or additional data are required, requests must be received within 30 days of acknowledgement as samples are not built ahead of the change. You may contact the PCN Manager or your local Field Sales Representative to acknowledge this PCN and request samples or additional data.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager ([PCN\\_ww\\_admin\\_team@list.ti.com](mailto:PCN_ww_admin_team@list.ti.com)).

Sincerely,

PCN Team  
SC Business Services

**20150112002  
Attachments**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
TL720M05QKVURQ1	null

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20150112002		<b>PCN Date:</b>	02/12/2015	
<b>Title:</b>	TLE4275QKVURQ1 Cu wire and Mold Compound change				
<b>Customer Contact:</b>	PCN_ww_admin_team@list.ti.com	<b>PCN Type:</b>	180 day	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	08/12/2015	<b>Estimated Sample Availability:</b>		Date provided at sample request	
<b>Change Type:</b>					
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process
<b>PCN Details</b>					
<b>Description of Change:</b>					
Texas Instruments Incorporated is announcing a change to TLE4275QKVURQ1 of the following materials.					
	<b>From:</b>		<b>To:</b>		
<b>Mold Compound</b>	SID# R-0		SID# R-23		
<b>Bond Wire</b>	Au		Cu		
<b>Reason for Change:</b>					
Continuity of supply. 1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties. 2) Maximize flexibility within our Assembly/Test production sites 3) Copper wire is easier to obtain and stock.					
<b>Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):</b>					
No anticipated impact.					
<b>Changes to product identification resulting from this PCN:</b>					
None					
<b>Product Affected:</b>					
TL720M05QKVURQ1		TL751M08QKVURQ1			
TL750M05QKVURQ1		TL751M12QKVURQ1			
TL750M08QKVURQ1		TL760M33QKVURQ1			
TL750M12QKVURQ1		TLE4275QKVURQ1			
TL751M05QKVURQ1					

**Automotive New Product Qualification Summary**  
(As per AEC-Q100 and JEDEC Guidelines)

This is for TLE4275QKVURQ1 Cu wire conversion  
Approved 12/15/2014

Attributes	Qual Device: TLE4275QKVURQ1
Qual ID	20140422-104102
Operating Temp Range	-40°C to +125°C
Automotive Grade Level	Grade 1
Wafer Fab Site	SFAB
Die Revision	D
Assembly Site	NFME
Package Type	LEADED
Package Designator	KVU
Ball/Lead Count	5

- QBS: Qual By Similarity

- Qual Device TLE4275QKVURQ1 is qualified at LEVEL3-260CG

**Qualification Results**

*Data Displayed as: Number of lots / Total sample size / Total failed*

Type	#	Test Spec	Min Lot Qty	SS/Lot	Test Name / Condition	Duration	Qual Device: TLE4275QKVURQ1
Qual ID							20140422-104102
<b>Test Group A - Accelerated Environment Stress Test</b>							
PC	A1	JESD22-113	-	-	PreCon Level 3	MSL3, 260C peak	3/all/0
HAST	A2	JESD22-A110	3	77	Biased HAST, 130C/85%RH	240 hrs	3/231/0
AC	A3	JESD22-A102	3	77	Autoclave 121C	240 hrs	3/231/0
TC	A4	JESD22-A104	3	77	Temperature Cycle, -65/150C	500 cycles	3/231/0
		MIL-STD883 Method 2011	1	30	Bond Pull	Post T/C 500 cycles	1/5/0
PTC	A5	JESD22-A105	1	45	Power Temperature Cycle, -40/125C	1000 cycles	1/50/0
HTSL	A6	JESD22-A103	1	45	High Temp Storage Bake 175C	500 hrs	1/45/0
<b>Test Group B - Accelerated Lifetime Simulation Test</b>							
<b>Test Group C - Package Assembly Integrity Tests</b>							
WBS	C1	AEC-Q100-001	1	30	Wire Bond Shear		Covered in Manufacturability Qualification
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull		Covered in Manufacturability Qualification
PD	C4	JESD22 B100 and B108	3	10	Auto Physical Dimensions	Cpk>1.33 Ppk>1.67	3/30/0
<b>Test Group D - Die Fabrication Reliability Tests</b>							
<b>Test Group E - Electrical Verification</b>							

ED	E5	AEC-Q100-009	3	30	Auto Electrical Distributions	Cpk>1.67 Room, hot test	1/30/0
<b>Additional Tests</b>							
MQ					Manufacturability (Auto Assembly)	(per automotive requirements)	3/all/0

**A1 (PC): Preconditioning:**

Performed for THB, Biased HAST, AC, uHAST & TC samples, as applicable.

**Ambient Operating Temperature by Automotive Grade Level:**

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

**E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):**

Room/Hot/Cold : HTOL

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

**Green/Pb-free Status:**

Qualified Pb-Free(SMT) and Green

TI Qualification ID: 20140422-104102

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

<b>Location</b>	<b>E-Mail</b>
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>